

In the Claims:

1. (Currently amended) An aqueous composition useful for polishing and removing copper on a semiconductor wafer comprising by weight percent up to 25 oxidizer, 0.05 to 1 inhibitor for a nonferrous metal, 0.01 to 5 complexing agent for the nonferrous metal, 0.01 to 5 modified cellulose, the modified cellulose being carboxy methyl cellulose having a degree of substitution of 0.1 to 3.0 and a molecular weight of 20K to 1000K, and balance water at a pH of 2 to 5, wherein said composition is abrasive free and free of polyacrylic acids.
2. Cancelled.
3. Cancelled.
4. (Currently amended) The composition of claim 3-1 wherein the carboxy methyl cellulose has a degree of substitution of 0.7 to 1.2 and a molecular weight of 40K to 250K.

5 to 10 Cancelled.